

MA4X1740G

Silicon planar type

For small power rectification and surge absorption

■ Features

- Two isolated elements contained in one package, allowing high-density mounting
- High breakdown voltage: $V_R = 200$ V

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	200	V
Repetitive peak reverse voltage		V_{RRM}	250	V
Non-repetitive peak reverse surge voltage		V_{RSM}	300	V
Output current	Single	I_O	100	mA
	Double		75	
Repetitive peak forward current	Single	I_{FRM}	225	mA
	Double		170	
Non-repetitive peak forward surge current *	Single	I_{FSM}	500	mA
	Double		375	
Junction temperature		T_j	125	$^\circ\text{C}$
Storage temperature		T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *: $t = 1$ s

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.3	V
Reverse current	I_R	$V_R = 200$ V			1.0	μA

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

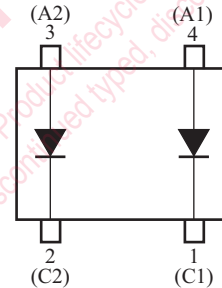
2. Absolute frequency of input and output is 3 MHz.

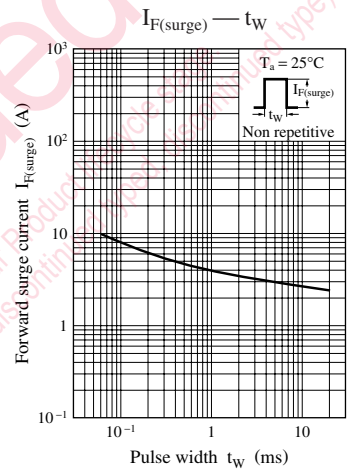
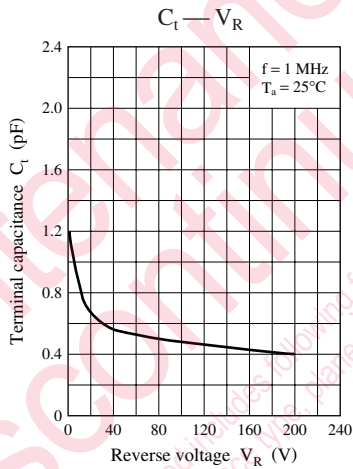
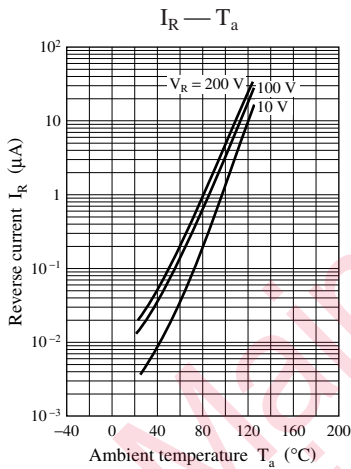
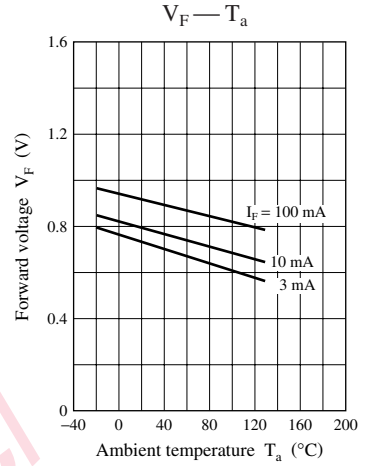
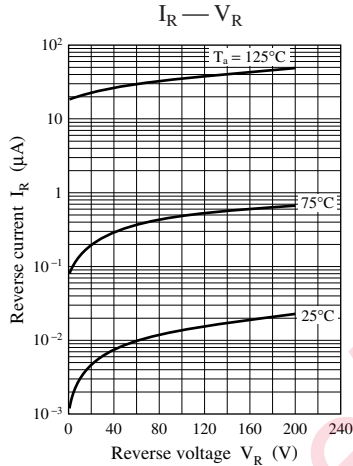
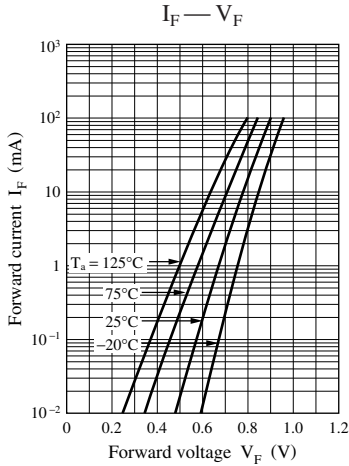
■ Package

- Code
Mini4-G3
- Pin Name
 - 1: Cathode 1
 - 2: Cathode 2
 - 3: Anode 2
 - 4: Anode 1

■ Marking Symbol: M20

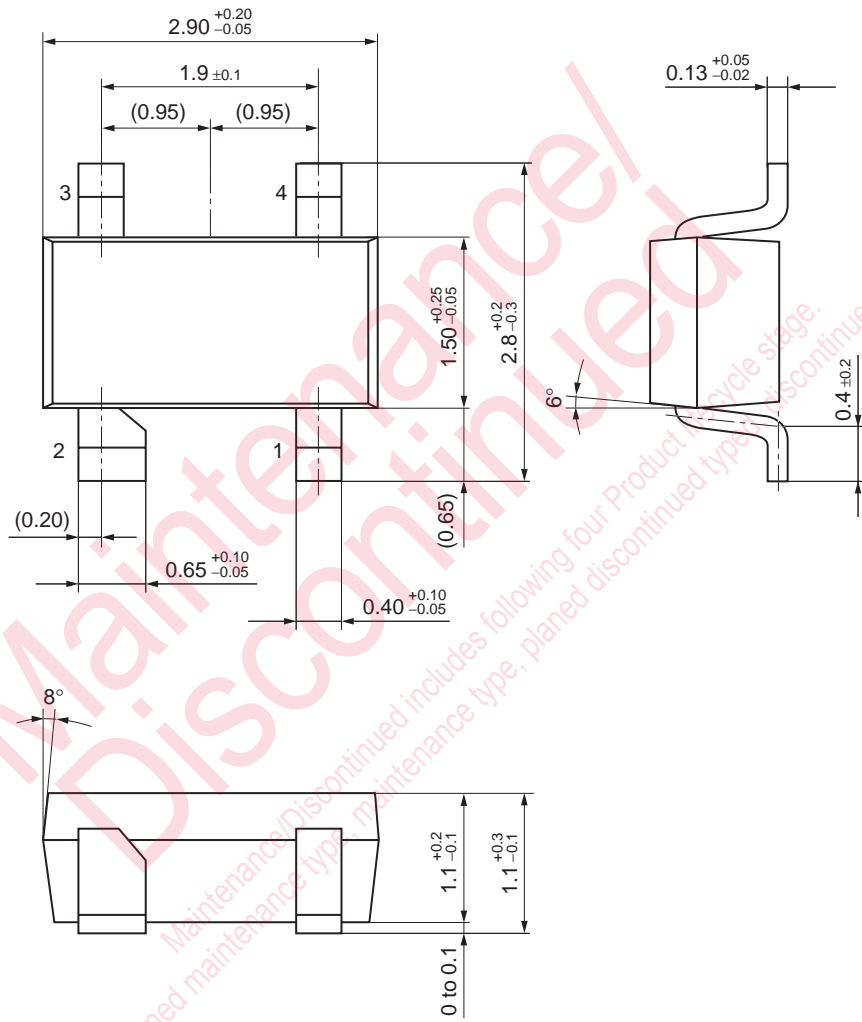
■ Internal Connection





Mini4-G3

Unit: mm



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